2SC4626J

Silicon NPN epitaxial planar type

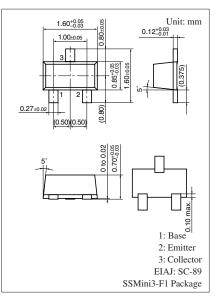
For high-frequency amplification

Features

- Optimum for RF amplification of FM/AM radios
- \bullet High transition frequency $f_{\rm T}$
- SS-Mini type package, allowing downsizing of the equipment and automatic insertion through the tape packing

Absolute Maximum Ratings $T_a = 25^{\circ}C$

Parameter	Symbol	Rating	Unit	
Collector-base voltage (Emitter open)	V _{CBO}	30	V	
Collector-emitter voltage (Base open)	V _{CEO}	20	V	
Emitter-base voltage (Collector open)	V _{EBO}	5	V	
Collector current	I _C	30	mA	
Collector power dissipation	P _C	125	mW	
Junction temperature	Tj	125	°C	
Storage temperature	T _{stg}	-55 to +125	°C	



Marking Symbol: V

Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

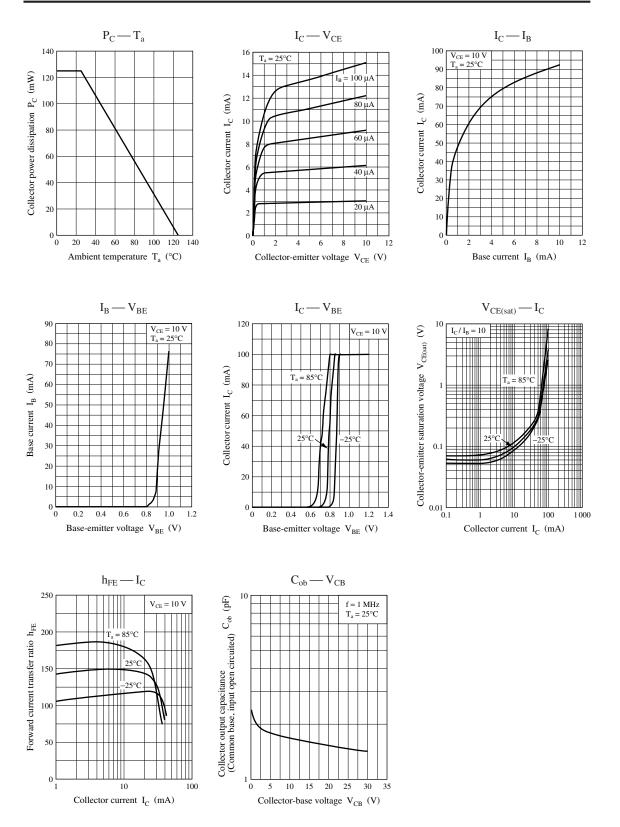
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base cutoff current (Emitter open)	I _{CBO}	$V_{CB} = 10 V, I_E = 0$			0.1	μΑ
Forward current transfer ratio *	h _{FE}	$V_{CB} = 10 \text{ V}, I_E = -1 \text{ mA}$	70		220	
Transition frequency	f _T	$V_{CB} = 10 \text{ V}, I_E = -1 \text{ mA}, f = 200 \text{ MHz}$	150	250		MHz
Noise figure	NF	$V_{CB} = 10 \text{ V}, I_E = -1 \text{ mA}, f = 5 \text{ MHz}$		2.8	4.0	dB
Reverse transfer impedance	Z _{rb}	$V_{CB} = 10 \text{ V}, I_E = -1 \text{ mA}, f = 2 \text{ MHz}$		22	50	Ω
Common-emitter reverse transfer capacitance	C _{re}	$V_{CB} = 10 \text{ V}, I_E = -1 \text{ mA}, f = 10.7 \text{ MHz}$		0.9	1.5	pF

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors. 2. *: Rank classification

Rank	В	С	No-rank
h _{FE}	70 to 140	110 to 220	70 to 220

Product of no-rank is not classified and have no indication for rank.

Panasonic



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